



JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

TO-3PK Plastic-Encapsulate Thyristors

BTA26 3Q TRIACs

MAIN CHARACTERISTICS

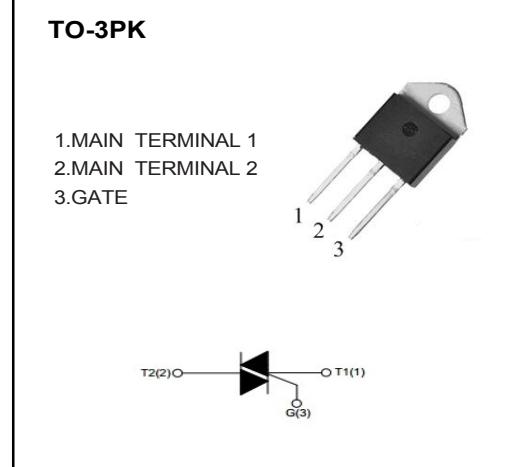
$I_{T(RMS)}$		25A
V_{DRM}/V_{RRM}	BTA26-600(C/B)W	600V
	BTA26-800(C/B)W	800V
V_{TM}		1.55V

FEATURES

- NPNPN 5-layer Structure TRIACs
- Mesa Glass Passivated Technology
- Multi Layers Metal Electrodes
- High Junction Temperature
- Good Commutation Performance
- High dV/dt and dl/dt
- Insulating Voltage=2500V_(RMS)

APPLICATIONS

- Heater Control
- Motor Speed Controller
- Mixer



MARKING



BTA26:Series Code
600CW:Depends on V_{DRM} and I_{GT}
XXX:Internal Code

ABSOLUTE RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test condition		Value		Unit
V_{DRM}/ V_{RRM}	Repetitive peak off-state voltage	$T_j=25^\circ\text{C}$	BTA26-600(C/B)W	600		V
			BTA26-800(C/B)W	800		V
$I_{T(RMS)}$	RMS on-state current	TO-3PK($T_c \leq 100^\circ\text{C}$), Fig. 1,2		25		A
I_{TSM}	Non repetitive surge peak on-state current	Full sine wave , $T_j(\text{init})=25^\circ\text{C}$, tp=20ms; Fig. 3,5		250		A
I^2t	I^2t value	tp=10ms		340		A^2s
dl_T/dt	Critical rate of rise of on-state current	$I_G=2*I_{GT}$, $tr \leq 10\text{ns}$, $F=120\text{Hz}$, $T_j=125^\circ\text{C}$		I - II - III	50	$\text{A}/\mu\text{s}$
I_{GM}	Peak gate current	tp=20 μs , $T_j=125^\circ\text{C}$		4		A
$P_{G(AV)}$	Average gate power	$T_j=125^\circ\text{C}$		1		W
T_{STG}	Storage temperature			-40~+150		$^\circ\text{C}$
T_j	Operating junction temperature			-40~+125		

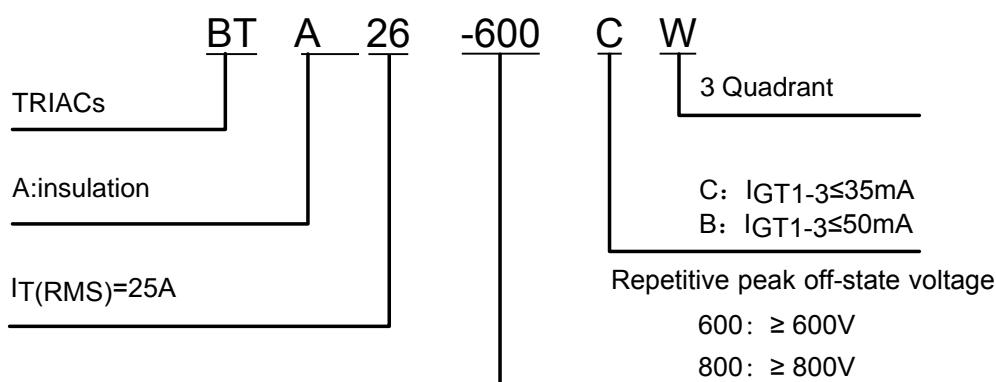
ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test condition	Value		Unit
			CW	BW	
I_{GT}	Gate trigger current	$V_D=12\text{V}$, $R_L=33\Omega$, $T_j=25^\circ\text{C}$, Fig. 6	≤ 35	≤ 50	mA
V_{GT}	Gate trigger voltage		≤ 1.3		V
V_{GD}	Non-triggering gate voltage	$V_D=V_{DRM}$, $T_j=125^\circ\text{C}$	≥ 0.2		V
I_H	Holding current	$I_T=500\text{mA}$, Fig. 6	≤ 50	≤ 75	mA
I_L	Latching current	$I_G=1.2I_{GT}$, Fig. 6	≤ 60	≤ 80	mA
			≤ 80	≤ 90	mA
dV_D/dt	Critical rate of rise of off-state	$V_D=67\%V_{DRM}$, Gate Open $T_j=125^\circ\text{C}$	≥ 500	≥ 1000	V/ μs
V_{TM}	On-state Voltage	$I_{TM}=35\text{A}$, $t_p=380\mu\text{s}$, Fig. 4	≤ 1.55		V
I_{DRM} / I_{RRM}	Repetitive peak off-state current	$V_D=V_{DRM}/V_{RRM}$, $T_j=25^\circ\text{C}$	≤ 5	≤ 5	μA
		$V_D=V_{DRM}/V_{RRM}$, $T_j=125^\circ\text{C}$	≤ 2.0	≤ 2.0	mA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th} (j-c)$	Junction to case (AC)	0.9	$^\circ\text{C/W}$
$R_{th} (j-a)$	Junction to ambient	50	$^\circ\text{C/W}$

PART NUMBER



CHARACTERISTICS CURVES

FIG.1: Maximum power dissipation versus RMS on-state current (full cycle)

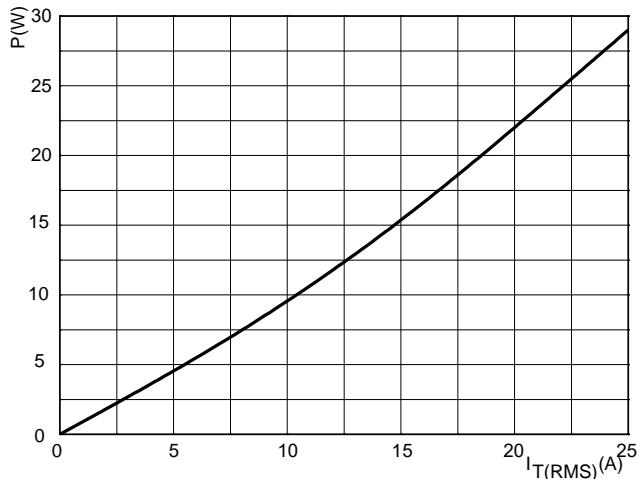


FIG.2: RMS on-state current versus case temperature (full cycle)

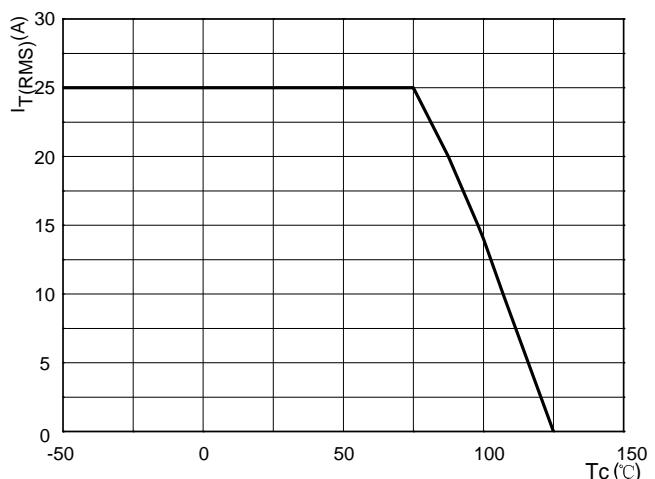


FIG.3: Surge peak on-state current versus number of cycles

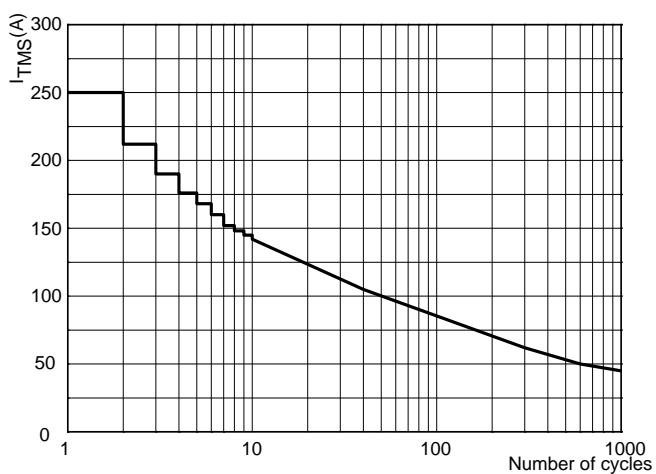


FIG.4: On-state characteristics (maximum values)

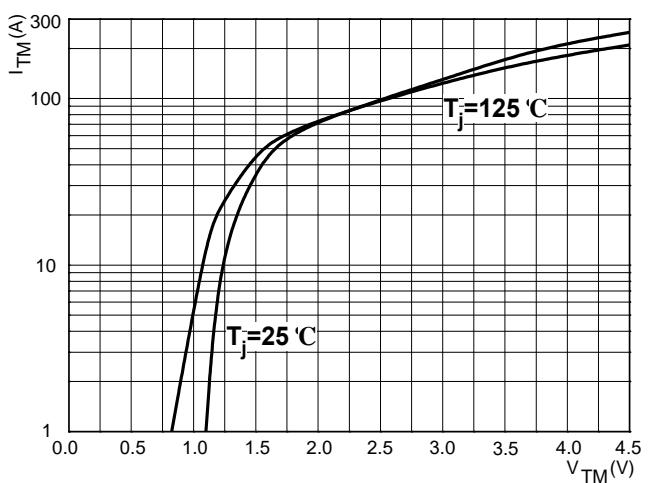


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$

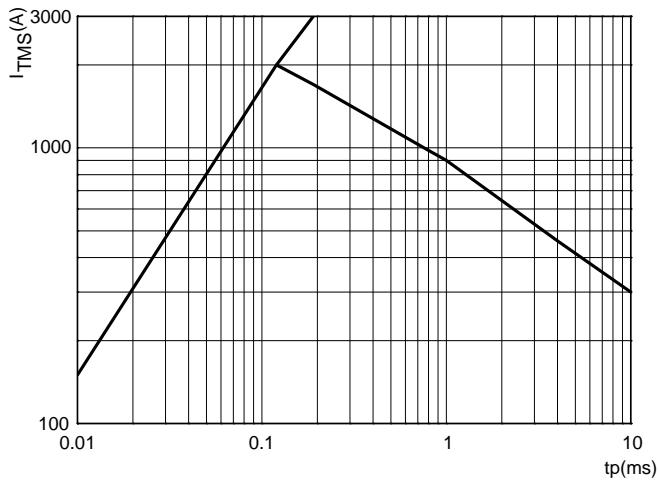
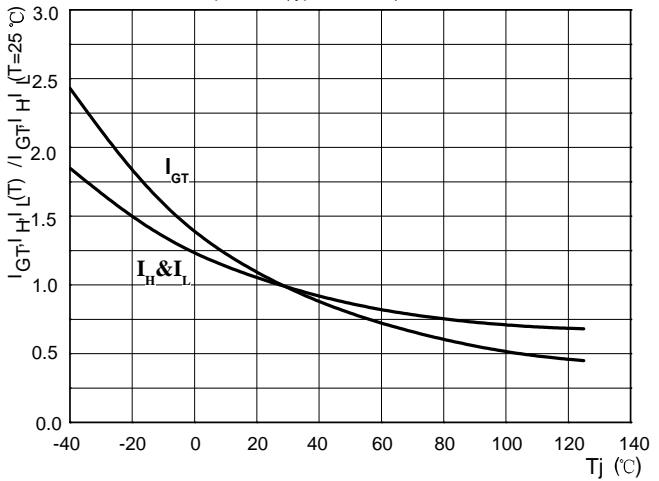
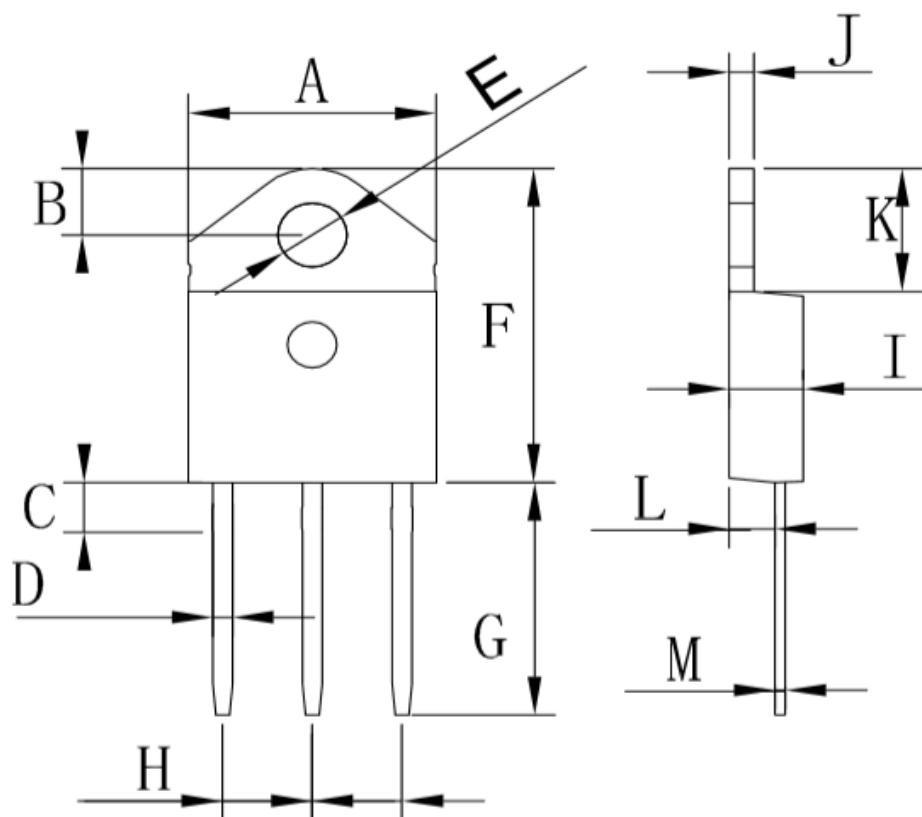


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature (typical values)



TO-3PK PACKAGE OUTLINE DIMENSIONS



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	14.9	15.35	0.586	0.604
B	4.1	4.65	0.161	0.183
C	2.5	3.2	0.098	0.125
D	1.12	1.32	0.044	0.051
E	4.12	4.31	0.162	0.169
F	20.21	20.75	0.795	0.816
G	15.02	15.55	0.591	0.612
H	5.35	5.62	0.210	0.221
I	4.38	4.65	0.172	0.183
J	1.42	1.62	0.055	0.063
K	7.85	8.22	0.309	0.323
L	2.71	2.92	0.106	0.114
M	0.52	0.68	0.020	0.026